

Notice of References Cited	Application/Control No. 10/598,124		Applicant(s)/Patent Under Reexamination SAKAMOTO ET AL.	
	Examiner YOSHITOSHI TAKEUCHI		Art Unit 1726	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
	U	Lee, Reflow Soldering Processes and Troubleshooting SMT, BGA, CSP and Flip Chip Technologies			
	V				
	W				
	X				

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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